NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL, PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (0.5um-7.6um) THICK,
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220